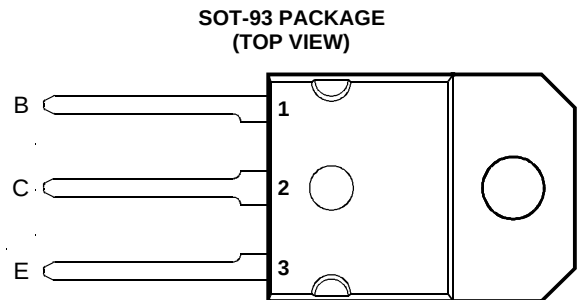


TIPL761B, TIPL761C NPN SILICON POWER TRANSISTORS

Copyright © 1997, Power Innovations Limited, UK

MAY 1989 - REVISED MARCH 1997

- Rugged Triple-Diffused Planar Construction
- 4 A Continuous Collector Current
- Operating Characteristics Fully Guaranteed at 100°C
- 1200 Volt Blocking Capability
- 100 W at 25°C Case Temperature



Pin 2 is in electrical contact with the mounting base.

MDTRAA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT
Collector-base voltage ($I_E = 0$)	TIPL761B	V_{CBO}	1100	V
	TIPL761C		1200	
Collector-emitter voltage ($V_{BE} = 0$)	TIPL761B	V_{CES}	1100	V
	TIPL761C		1200	
Collector-emitter voltage ($I_B = 0$)	TIPL761B	V_{CEO}	500	V
	TIPL761C		550	
Emitter-base voltage		V_{EBO}	10	V
Continuous collector current		I_C	4	A
Peak collector current (see Note 1)		I_{CM}	8	A
Continuous device dissipation at (or below) 25°C case temperature		P_{tot}	100	W
Operating junction temperature range		T_j	-65 to +150	°C
Storage temperature range		T_{stg}	-65 to +150	°C

NOTE 1: This value applies for $t_p \leq 10$ ms, duty cycle $\leq 2\%$.

PRODUCT INFORMATION

Information is current as of publication date. Products conform to specifications in accordance with the terms of Power Innovations standard warranty. Production processing does not necessarily include testing of all parameters.



TIPL761B, TIPL761C

NPN SILICON POWER TRANSISTORS

MAY 1989 - REVISED MARCH 1997

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{CE(sus)}$ Collector-emitter sustaining voltage	$I_C = 10\text{ mA}$ $L = 25\text{ mH}$ (see Note 2) TIPL761B TIPL761C	500 550			V
I_{CES} Collector-emitter cut-off current	$V_{CE} = 1100\text{ V}$ $V_{BE} = 0$ TIPL761B $V_{CE} = 1200\text{ V}$ $V_{BE} = 0$ TIPL761C $V_{CE} = 1100\text{ V}$ $V_{BE} = 0$ $T_C = 100^\circ\text{C}$ TIPL761B $V_{CE} = 1200\text{ V}$ $V_{BE} = 0$ $T_C = 100^\circ\text{C}$ TIPL761C			50 50 200 200	μA
I_{CEO} Collector cut-off current	$V_{CE} = 500\text{ V}$ $I_B = 0$ TIPL761B $V_{CE} = 550\text{ V}$ $I_B = 0$ TIPL761C			50 50	μA
I_{EBO} Emitter cut-off current	$V_{EB} = 10\text{ V}$ $I_C = 0$			1	mA
h_{FE} Forward current transfer ratio	$V_{CE} = 5\text{ V}$ $I_C = 0.5\text{ A}$ (see Notes 3 and 4)	20		60	
$V_{CE(sat)}$ Collector-emitter saturation voltage	$I_B = 0.4\text{ A}$ $I_C = 2\text{ A}$ $I_B = 0.6\text{ A}$ $I_C = 3\text{ A}$ (see Notes 3 and 4) $I_B = 0.6\text{ A}$ $I_C = 3\text{ A}$ $T_C = 100^\circ\text{C}$			1.0 2.5 5.0	V
$V_{BE(sat)}$ Base-emitter saturation voltage	$I_B = 0.4\text{ A}$ $I_C = 2\text{ A}$ $I_B = 0.6\text{ A}$ $I_C = 3\text{ A}$ (see Notes 3 and 4) $I_B = 0.6\text{ A}$ $I_C = 3\text{ A}$ $T_C = 100^\circ\text{C}$			1.2 1.4 1.3	V
f_t Current gain bandwidth product	$V_{CE} = 10\text{ V}$ $I_C = 0.5\text{ A}$ $f = 1\text{ MHz}$		12		MHz
C_{ob} Output capacitance	$V_{CB} = 20\text{ V}$ $I_E = 0$ $f = 0.1\text{ MHz}$		110		pF

NOTES: 2. Inductive loop switching measurement.

3. These parameters must be measured using pulse techniques, $t_p = 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

thermal characteristics

PARAMETER	MIN	TYP	MAX	UNIT
$R_{\theta JC}$ Junction to case thermal resistance			1.25	$^\circ\text{C/W}$

inductive-load-switching characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS [†]	MIN	TYP	MAX	UNIT
t_{SV} Voltage storage time	$I_C = 3\text{ A}$ $I_{B(on)} = 0.6\text{ A}$ (see Figures 1 and 2) $V_{BE(off)} = -5\text{ V}$			2.5	μs
t_{rV} Voltage rise time				300	ns
t_{fi} Current fall time				250	ns
t_{ti} Current tail time				150	ns
t_{xo} Cross over time				400	ns
t_{SV} Voltage storage time	$I_C = 3\text{ A}$ $I_{B(on)} = 0.6\text{ A}$ (see Figures 1 and 2) $V_{BE(off)} = -5\text{ V}$ $T_C = 100^\circ\text{C}$			3	μs
t_{rV} Voltage rise time				500	ns
t_{fi} Current fall time				250	ns
t_{ti} Current tail time				150	ns
t_{xo} Cross over time				750	ns

[†] Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

PRODUCT INFORMATION

Adjust pw to obtain I_C

For $I_C < 6 \text{ A}$ $V_{CC} = 50 \text{ V}$
 For $I_C \geq 6 \text{ A}$ $V_{CC} = 100 \text{ V}$

The diagram shows three vertically aligned waveforms for a BJT switching circuit. The top waveform is the Base Current (I_B), which starts at a low level, rises to a plateau at $I_{B(on)}$, and then falls back to the low level. The middle waveform is the Collector Voltage (V_{CE}), which starts at a high level, drops to a minimum during the base current plateau, and then rises back to the high level. The bottom waveform is the Collector Current (I_C), which starts at a low level, rises to a peak during the base current plateau, and then falls back to the low level. A vertical dashed line marks the start of the base current fall. Points A, B, C, D, E, and F are marked on the waveforms with their corresponding percentages: A (90%) on I_B , B (10%) on V_{CE} , C (90%) on I_C , D (90%) on I_C , E (10%) on I_C , and F (2%) on I_C . The time intervals between these points are labeled as t_{sv} , t_{rv} , t_{fi} , t_{ti} , and t_{xo} .

Base Current

Collector Voltage

Collector Current

A (90%)

B (10%)

C (90%)

D (90%)

E (10%)

F (2%)

$I_{B(on)}$

I_B

V_{CE}

$I_{C(on)}$

A - B = t_{sv}

B - C = t_{rv}

D - E = t_{fi}

E - F = t_{ti}

B - E = t_{xo}

Figure 2. Inductive-Load Switching Waveforms

TIPL761B, TIPL761C NPN SILICON POWER TRANSISTORS

MAY 1989 - REVISED MARCH 1997

TYPICAL CHARACTERISTICS

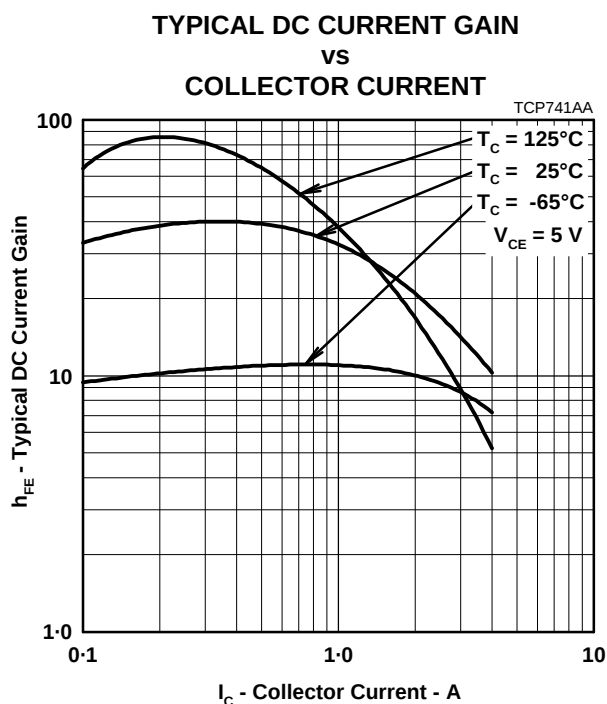


Figure 3.

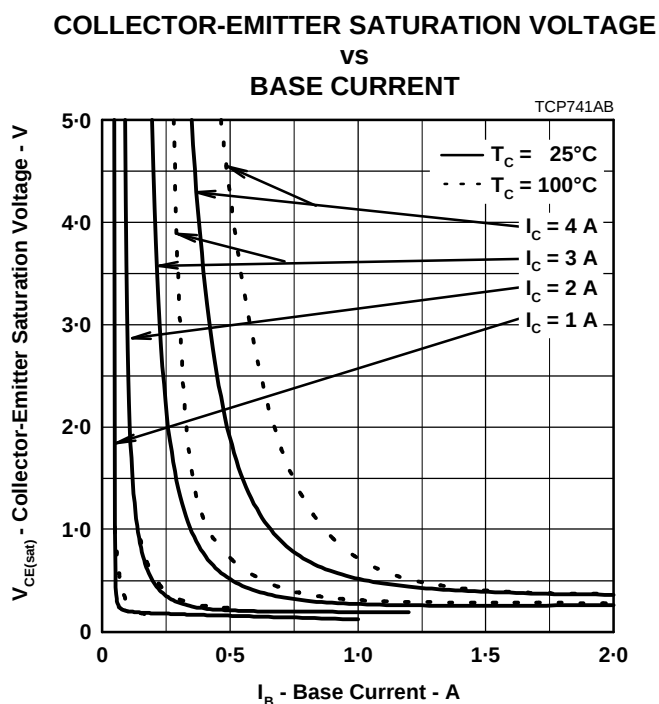


Figure 4.

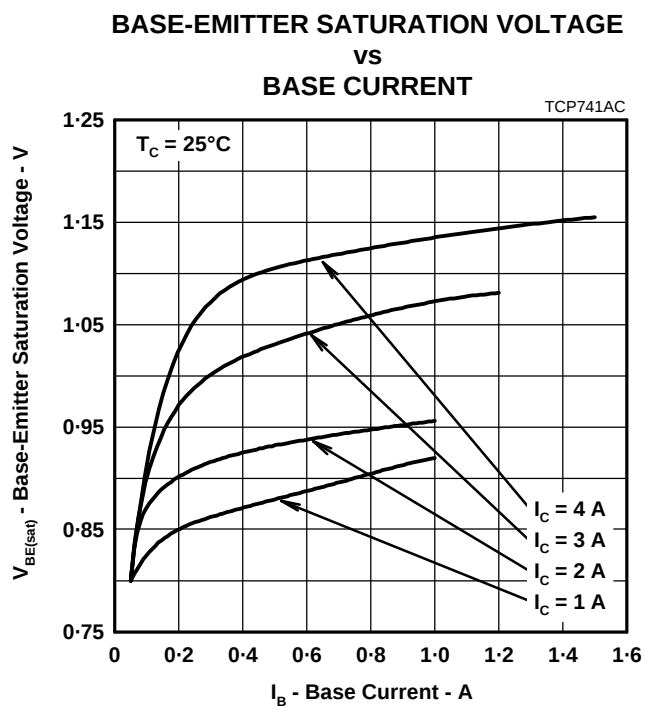


Figure 5.

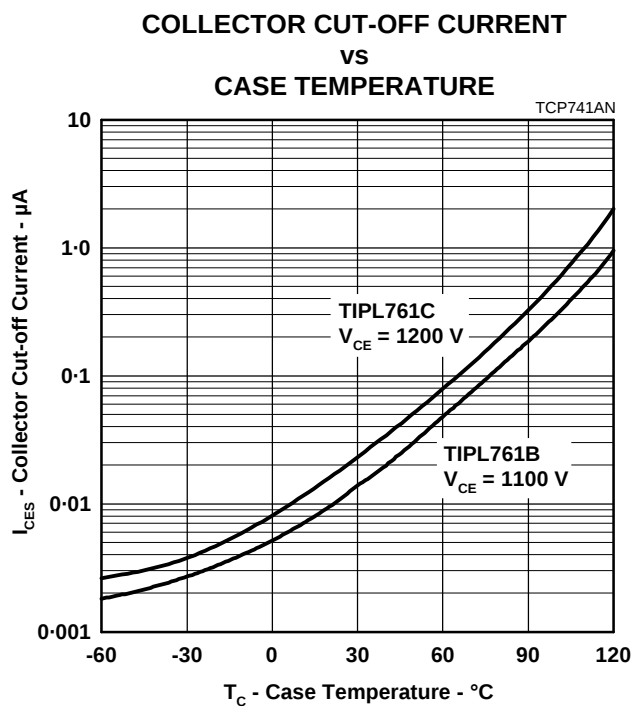
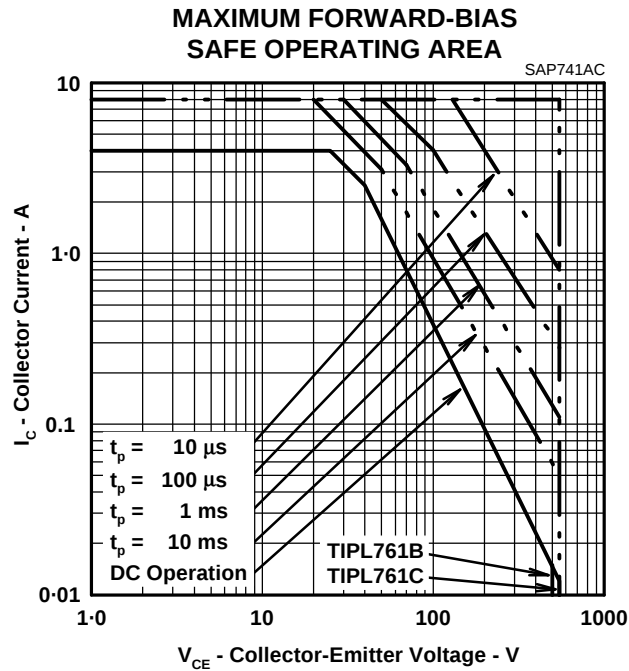


Figure 6.

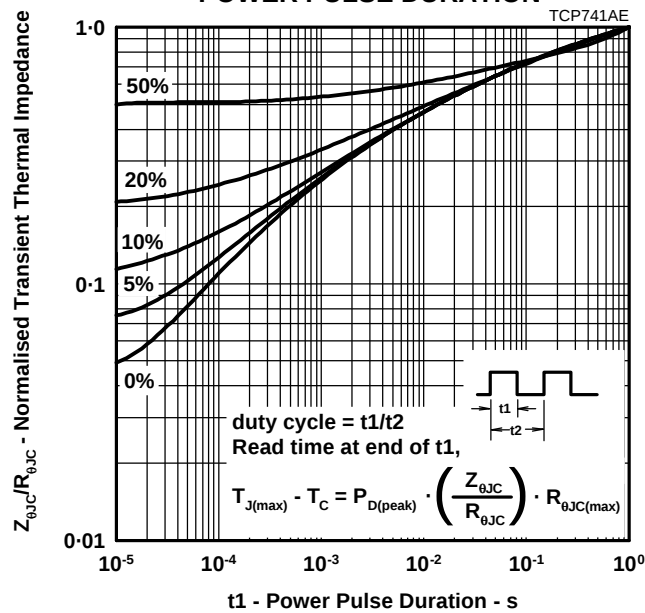
PRODUCT INFORMATION

MAXIMUM SAFE OPERATING REGIONS



THERMAL INFORMATION

THERMAL RESPONSE JUNCTION TO CASE VS POWER PULSE DURATION



TIPL761B, TIPL761C

NPN SILICON POWER TRANSISTORS

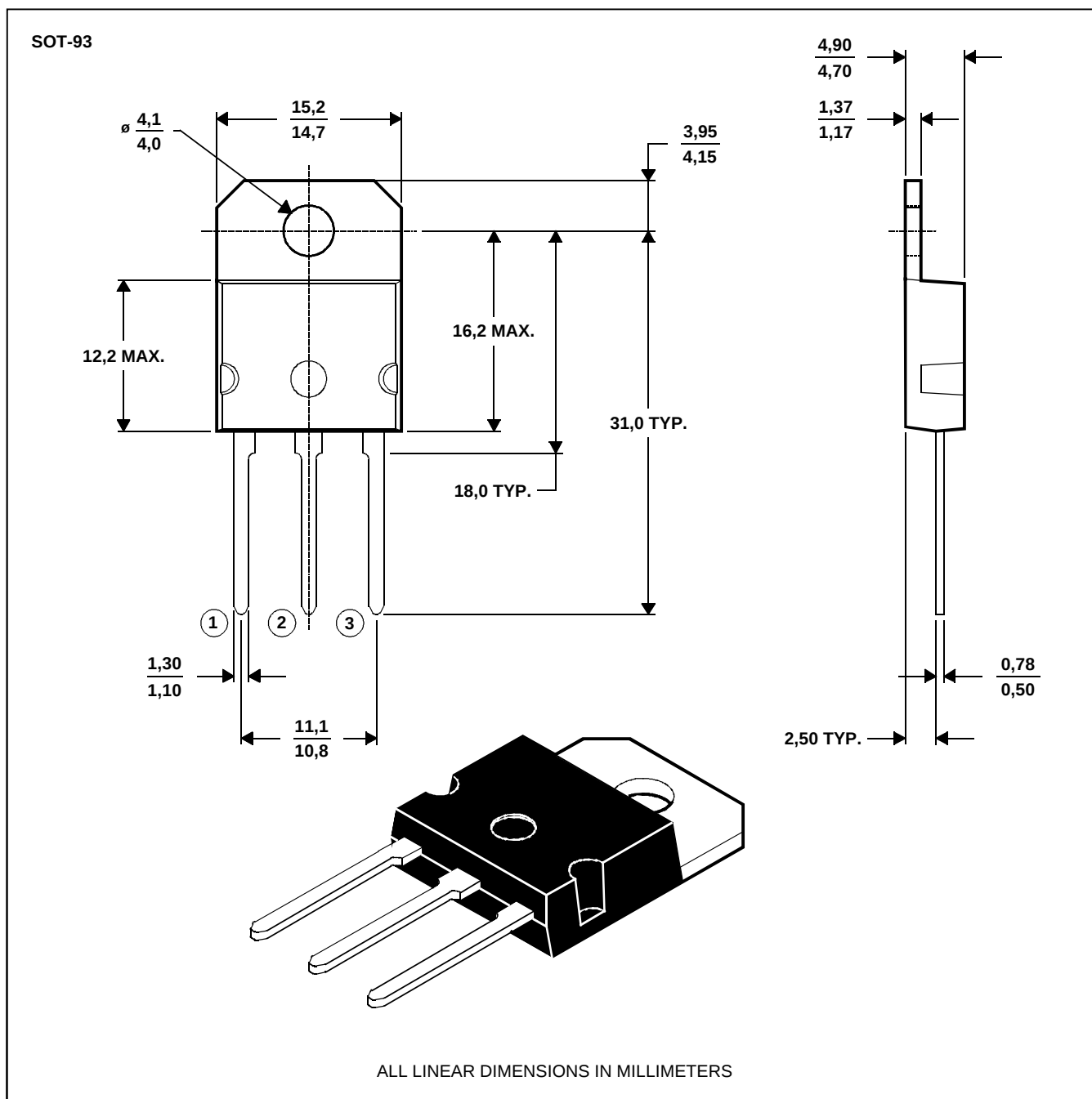
MAY 1989 - REVISED MARCH 1997

MECHANICAL DATA

SOT-93

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

MDXXAW

PRODUCT INFORMATION

IMPORTANT NOTICE

Power Innovations Limited (PI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to verify, before placing orders, that the information being relied on is current.

PI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with PI's standard warranty. Testing and other quality control techniques are utilized to the extent PI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except as mandated by government requirements.

PI accepts no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor is any license, either express or implied, granted under any patent right, copyright, design right, or other intellectual property right of PI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS.

Copyright © 1997, Power Innovations Limited